PCN Number:	2022121900	03.1	PCN Date: December 22, 2022						
Title: Qualification	, 5								
Customer Contact:	PCN Manager	Dept:	Quality Services						
Proposed 1 st Ship Dat	e: Mar 22, 2023		Sample requests accepted until: Jan 22, 20		Jan 22, 2023*				
	ived after (Jan 22, 2023) will not be suppor			orted.					
Change Type:									
Assembly Site		Design			Wafer Bump Site				
Assembly Process Assembly Materials	、	Data She	et nber change		Wafer Bump Material Wafer Bump Process				
Mechanical Specific		Test Site			Wafer Fab Site				
Packing/Shipping/L		Test Pro			Wafer Fab Mater	ials			
					Wafer Fab Proce				
		PCN	Details						
Description of Change	:								
Texas Instruments Incorporated is announcing the qualification TI CDAT as Additional Assembly Site for select device listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.									
	oly Site Origin	-	Country Code	As	sembly Site City				
ASEN	ASN		CHN		Suzhou				
TICDAT	CDA	C	CHN		Chengdu				
Material Differences:									
	ASEN	1	TI CDAT						
Wire type	1.0 mil .	Au	0.8mil Cu						
Mount Compound	1400230	112	4207123						
Mold Compound	1800819	111	4222198						
Reason for Change:									
Continuity of supply.									
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):									
None									
Impact on Environmental Ratings:									
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.									
RoHS		-	Green Sta		IEC 62474	4			
🛛 No Change	🛛 No Char	nge	🛛 No Change	9	🛛 🛛 No Change				
Changes to product id	entification	resulting fr	om this PCN:						

ASEN	Assembly Si	Assembly Site Origin (22L) Assembly Site Origin (22L)		ASO: ASN	
TI-CDAT	Assembly Si			ASO: CDA	
Sample product shipping TEXAS INSTRUMENTS MADE IN: Malaysia 20: 20: MSL 2 /260C/1 YEAR MSL 1 /235C/UNLIM 03/29/C OPT: ITEM: 39 LBL: 5A (L)T0:1750		1P) SN74LS07N (Q) 2000 (31T) LOT: 3959 4W) TKY (1T) 7 P) 2P) REV: (V) 20L) CSO: SHE (21	D) 0336 0047MLA 523483512		
Product Affected:					
ESD401DPYR	<pre>FPD1E01B04DPYT</pre>	TPD1E0B04D	PYT		

Qualification Report Approve Date 29-Jul-2022

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

			Dutu	Dispidy	ca as. Name		otar sumple si		<i>а</i>	
Typ e	#	Test Name	Conditio n	Durat ion	Qual Device: <u>TPD1E01B0</u> <u>4DPYR</u>	QBS Reference: <u>TPS2546</u> Q <u>R</u> <u>TERQ1</u>	QBS Reference: <u>PTPDTESTUL</u> <u>CD</u> Q <u>AR</u>	QBS Reference: <u>TCAN1048AVD</u> <u>MTRQ1</u>	QBS Reference: <u>TPD1E04U0</u> <u>4DPYR</u>	QBS Reference: <u>TPD1E01B0</u> <u>4DPLR</u>
HA ST	A2	Biased HAST	130C/85 %RH	96 Hours	-	3/231/0	3/231/0	1/77/0	-	-
UHA ST	A3	Autoclave	121C/15 psig	96 Hours	-	3/231/0	3/231/0	1/77/0	-	-
тс	A4	Temperatu re Cycle	- 65C/150 C	500 Cycle s	-	3/231/0	3/231/0	1/77/0	-	-
HT SL	A6	High Temperatu re Storage Life	150C	1000 Hours	-	3/135/0	3/231/0	1/45/0	-	-
HT OL	B1	Life Test	125C	1000 Hours	-	3/231/0	_	1/77/0	-	-
HT OL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	-	-
ELF R	B2	Early Life Failure Rate	125C	48 Hours	-	1/800/0	-	-	-	-
WB S	C 1	Ball Shear	76 balls, 3 units min	Wires	1/76/0	-	-	-	1/76/0	-

WB P	C 2	Bond Pull	30 Wires, 3 units min	Wires	-	-	3/90/0	-	-	-
WB P	C 2	Bond Pull	76 Wires, 3 units min	Wires	3/228/0	-	-	-	1/76/0	-
SD	C 3	PB Solderabili ty	Precond ition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-
SD	C 3	PB-Free Solderabili ty	Precond ition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-
PD	C 4	Physical Dimension s	(per mechani cal drawing)	-	-	-	-	-	1/5/0	-
PD	C 4	Physical Dimension s	Cpk>1.6 7	-	-	3/30/0	-	-	-	-
ES D	E2	ESD CDM	-	1500 Volts	-	-	3/9/0	1/3/0	-	-
ES D	E2	ESD CDM	-	250 Volts	-	-	-	-	-	1/3/0
ES D	E2	ESD CDM	-	500 Volts	-	1/3/0	-	-	-	-
ES D	E2	ESD HBM	-	1000 Volts	-	-	-	-	-	1/3/0
ES D	E2	ESD HBM	-	1200 0 Volts	-	-	-	1/3/0	-	-
ES D	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-	-	-
ES D	E2	ESD HBM	-	4000 Volts	-	-	3/9/0	1/3/0	-	-
CH AR	E5	Electrical Characteri zation	Per Datashe et Paramet ers	-	-	-	-	-	-	1/30/0
CH AR	E5	Electrical Distributio ns	Cpk>1.6 7 Room, hot, and cold	-	-	3/90/0	-	3/90/0	-	-

QBS: Qual By Similarity Qual Device TPD1E01B04DPYR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	PCN ww admin team@list.ti.com

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any daims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (<u>www.ti.com/legal/termsofsale.html</u>) or other applicable terms available either on <u>ti.com</u> or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.